



<b>Form Type</b>	Distribute	<b>Version</b>	2.0	<b>Ref</b>	IPC 1752A	<b>Sectionals</b>	Manufacturing Info/ Material Info	<b>Subsectionals</b>	D, A
<b>Supplier Information</b>									
<b>Company Name</b>	TE Connectivity	<b>Request Document ID</b>		<b>Contact Name</b>	John R. Penica	<b>Contact Title</b>	Mgr Global Product Compliance		
<b>Company Unique ID</b>	-	<b>Response Date</b>	2014-05-12	<b>Contact Email</b>	jrpenica@te.com				
<b>Contact Phone Number</b>	1-717-592-3266								
<b>Legal Statement</b>									
<b>Supplier Acceptance</b>	true								
<b>Legal Statement</b>									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
<b>Product</b>									
<b>Manufacturer Item number</b>	170361-3	<b>Amount</b>	162.0	<b>Version</b>	-	<b>Identity</b>			
<b>Manufacturer Item Name</b>		<b>Weight Uom</b>	mg	<b>Mfr Site</b>		<b>Authority</b>			
<b>Date</b>		<b>UOM</b>	Each						
<b>EURoHS-0508</b>	Product(s) meets EU RoHS requirement without any exemptions - true								
<b>ChinaRoHS-0508</b>	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products - true								
<b>Manufacturing Information</b>									
<b>J-STD-020 MSL Rating</b>		<b>Max Total a Wave Time</b>		<b>Ramp Rate</b>		<b>Wave Additional Info</b>			
<b>Classification Temp</b>		<b>Max Wave Solder Time</b>	0.0	<b>Ramp Down Rate</b>		<b>Psi Rating Reflow</b>			
<b>Max Time Within 5</b>		<b>Psi Rating Wave</b>		<b>Package Designator</b>		<b>Size</b>	0.0		
<b>Time Above 217</b>		<b>Reflow Additional Info</b>		<b>Preheat Max Temp</b>		<b>Terminal Base Alloy</b>	NAC		
<b>Preheat Duration</b>		<b>bulk Solder Termination</b>	NAC	<b>Nbr or Reflow Cycles</b>		<b>Terminal Plating</b>	NAC		
<b>Preheat Min Temp</b>		<b>Nbr of Instances</b>	0	<b>Component Temp Spike</b>		<b>Shape</b>	NAC		
<b>Product Disclosure</b>									
<b>Sub-Item/Material/Substance</b>	<b>Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Material	1	Nickel Plate				1.0	2.564	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.005128	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.002564	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.7	1.0	2.55631	mg	
Material	1	Brass				1.0	159.143	mg	
Substance	2	Chromium	Supplier	7440-47-3	0.0010	1.0	0.00159143	mg	
Substance	2	Zinc	Supplier	7440-66-6	28.0225	1.0	44.59585	mg	
Substance	2	Manganese	Supplier	7439-96-5	0.05	1.0	0.0795715	mg	
Substance	2	Antimony	Supplier	7440-36-0	0.01	1.0	0.0159143	mg	
Substance	2	Iron	Supplier	7439-89-6	0.05	1.0	0.0795715	mg	
Substance	2	Cobalt	Supplier	7440-48-4	0.1	1.0	0.15914	mg	
Substance	2	Beryllium	Supplier	7440-41-7	0.0010	1.0	0.00159143	mg	
Substance	2	Copper	Supplier	7440-50-8	71.5	1.0	113.78724	mg	
Substance	2	Arsenic	Supplier	7440-38-2	0.01	1.0	0.0159143	mg	
Substance	2	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	7.9571E-4	mg	
Substance	2	Nickel	Nickel	7440-02-0	0.2	1.0	0.31829	mg	
Substance	2	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0050	1.0	0.00795715	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.05	1.0	0.0795715	mg	
Material	1	Gold Plate				1.0	0.293	mg	
Substance	2	Gold	Supplier	7440-57-5	99.0	1.0	0.29007	mg	

Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	1.0	1.0	0.00293	mg	
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